

**Amendments to the Specification**

Please add the following new paragraph after the Title at page 1:

**--CROSS-REFERENCE TO RELATED APPLICATIONS**

This application is a division of U.S. Patent Application Serial No. 10/132,834, filed April 25, 2002. --

Please replace the paragraph at page 10, lines 25-30, with the following amended paragraph:

In another example of a die construction and package illustrated in **FIGS. 9-12**, a semiconductor die 12a', 12b' can be mounted on the upper surface 32' of a support substrate 34' (e.g., polyimide tape, etc.) ~~through~~ having an opening 36' formed by stamping, for example, using a dielectric adhesive 38' (e.g., paste or double-sided tape), or conductive bumps as described for **FIGS. 3-5**. The semiconductor die 12a', 12b' includes bond pads 40' electrically connected by wire bonds 42' to bond pads 44' on the underside 46' of the support